

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A production method of an electronic device having an internal electrode, comprising the steps of:

forming a release layer on a surface of a first supporting sheet;

forming an electrode layer on a surface of said release layer;

pressing said electrode layer against a surface of a green sheet to bond said electrode layer with the surface of said green sheet;

stacking the green sheets bonded with said electrode layer to form a green chip; and

firing said green chip;

wherein

before pressing said electrode layer against the surface of said green sheet, an adhesive layer is formed on a surface of said electrode layer or a surface of said green sheet by a transfer method.

2. (Original) The production method of an electronic device having an internal electrode as set forth in claim 1, wherein:

to form said green chip, a step of pressing another electrode layer to be bonded against an opposite surface of the electrode layer side of the green sheet bonded with said electrode layer so as to bond the electrode layer via an adhesive layer formed by the transfer method, and a step of pressing the electrode layer against another green sheet so as to bond via an adhesive layer formed by the transfer method are repeated.

3. (Original) The production method of an electronic device having an internal electrode as set forth in claim 1, wherein:

to form said green chip, a step of pressing another green sheet to be bonded against a surface on the electrode layer side of the green sheet bonded with said electrode layer so as to bond the green sheet via an adhesive layer formed by the transfer method, and a step of pressing another electrode layer against the green sheet so as to bond via an adhesive layer formed by the transfer method are repeated.

4. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 3~~claim 1, wherein

said green sheet is formed on a surface of a second supporting sheet in a releasable way and, after said electrode layer is bonded with a surface of said green sheet, said second supporting sheet is released from the surface of said green sheet.

5. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 4~~claim 1, wherein

said adhesive layer is formed on a surface of a third supporting sheet in a releasable way first and pressed against a surface of said green sheet or a surface of said electrode layer so as to be bonded.

6. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 5~~claim 1, wherein a thickness of said adhesive layer is 0.02 to 0.3 μm .

7. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 6~~claim 1, wherein

said electrode layer is formed to be a predetermined pattern on a surface of said release layer, and a blank pattern layer having substantially the same thickness as that of said electrode layer is formed on a surface of the release layer not formed with the electrode layer.

8. (Original) The production method of an electronic device having an internal electrode as set forth in claim 7, wherein said blank pattern layer includes substantially the same dielectrics as that composing said green sheet.

9. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in claim 7 ~~or 8~~, wherein said blank pattern layer includes substantially the same binder as that of said green sheet.

10. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 9~~claim 1, wherein said release layer includes substantially the same dielectrics as that composing said green sheet.

11. (Original) The production method of an electronic device having an internal electrode as set forth in claim 10, wherein said release layer includes substantially the same binder resin as that included in said green sheet.

12. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 11~~claim 1, wherein said adhesive layer includes substantially the same binder resin as that included in said green sheet.

13. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 12~~claim 1, wherein said electrode layer includes substantially the same binder resin as that included in said green sheet.

14. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 9 and 11 to 13~~claim 9, wherein said binder resin includes a butyral based resin.

15. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 14~~claim 1, wherein a thickness of said green sheet is 3 μm or thinner.

16. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 15~~claim 1, wherein a thickness of said release layer is not thicker than a thickness of said electrode layer.

17. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 16~~claim 1, wherein a pressure at the time of bonding said electrode layer with a surface of said green sheet is 0.2 to 15 MPa.

18. (Currently Amended) The production method of an electronic device having an internal electrode as set forth in ~~any one of claims 1 to 17~~claim 1, wherein a pressing temperature at the time of bonding said electrode layer with a surface of said green sheet is 40 to 100°C.